

NB2305A

3.3 V Zero Delay Clock Buffer

The NB2305A is a versatile, 3.3 V zero delay buffer designed to distribute high-speed clocks. It accepts one reference input and drives out five low-skew clocks. It is available in a 8 pin package.

The -1H version of the NB2305A operates at up to 133 MHz, and has higher drive than the -1 devices. All parts have on-chip PLL's that lock to an input clock on the REF pin. The PLL feedback is on-chip and is obtained from the CLKOUT pad.

Multiple NB2305A devices can accept the same input clock and distribute it. In this case the skew between the outputs of the two devices is guaranteed to be less than 700 ps.

All outputs have less than 200 ps of cycle-to-cycle jitter. The input and output propagation delay is guaranteed to be less than 350 ps, and the output to output skew is guaranteed to be less than 250 ps.

The NB2305A is available in two different configurations, as shown in the ordering information table. The NB2305A1 is the base part. The NB2305Ax1H* is the high drive version of the -1 and its rise and fall times are much faster than -1 part.

Features

- 15 MHz to 133 MHz Operating Range, Compatible with CPU and PCI Bus Frequencies
- Zero Input - Output Propagation Delay
- Multiple Low-Skew Outputs
- Output-Output Skew Less than 250 ps
- Device-Device Skew Less than 700 ps
- One Input Drives 5 Outputs
- Less than 200 ps Cycle-to-Cycle Jitter is Compatible with Pentium® Based Systems
- Available in 8 Pin, 150 mil SOIC Package and 8 Pin TSSOP 4.4 mm
- 3.3 V Operation, Advanced 0.35 μ CMOS Technology
- These are Pb-Free Devices



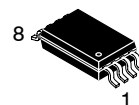
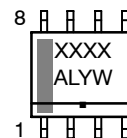
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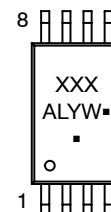
MARKING DIAGRAMS*



SOIC-8
D SUFFIX
CASE 751



TSSOP-8
DT SUFFIX
CASE 948J



XXXX = Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb-Free Package
(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

*x = C for Commercial; I for Industrial.

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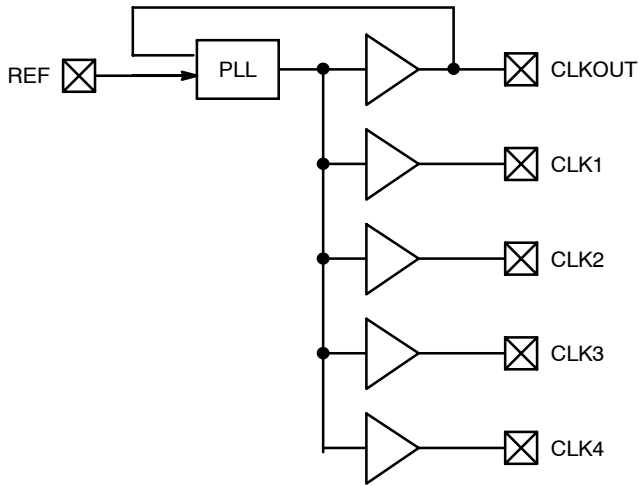


Figure 1. Block Diagram

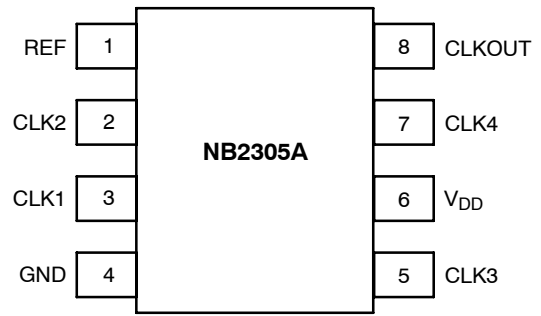


Figure 2. Pin Configuration

Table 1. PIN DESCRIPTION

| Pin # | Pin Name | Description |
|-------|-----------------|---|
| 1 | REF (Note1) | Input reference frequency, 5 V tolerant input. |
| 2 | CLK2 (Note 2) | Buffered clock output. |
| 3 | CLK1 (Note 2) | Buffered clock output. |
| 4 | GND | Ground. |
| 5 | CLK3 (Note 2) | Buffered clock output. |
| 6 | V _{DD} | 3.3 V supply. |
| 7 | CLK4 (Note 2) | Buffered clock output. |
| 8 | CLKOUT (Note 2) | Buffered clock output, internal feedback on this pin. |

1. Weak pulldown.
2. Weak pulldown on all outputs.

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Table 2. MAXIMUM RATINGS

| Parameter | Min | Max | Unit |
|---|------|----------------|------|
| Supply Voltage to Ground Potential | -0.5 | +7.0 | V |
| DC Input Voltage (Except REF) | -0.5 | $V_{DD} + 0.5$ | V |
| DC Input Voltage (REF) | -0.5 | 7 | V |
| Storage Temperature | -65 | +150 | °C |
| Maximum Soldering Temperature (10 sec) | | 260 | °C |
| Junction Temperature | | 150 | °C |
| Static Discharge Voltage (per MIL-STD-883, Method 3015) | | >2000 | V |

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 3. OPERATING CONDITIONS FOR COMMERCIAL AND INDUSTRIAL TEMPERATURE DEVICES

| Parameter | Description | Min | Max | Unit |
|-----------|---|--------------------------|---------------|------|
| V_{DD} | Supply Voltage | 3.0 | 3.6 | V |
| T_A | Operating Temperature (Ambient Temperature) | Commercial Industrial | 0 70 85 | °C |
| C_L | Load Capacitance, below 100 MHz | | 30 | pF |
| C_L | Load Capacitance, from 100 MHz to 133 MHz | | 10 | pF |
| C_{IN} | Input Capacitance | | 7 | pF |

Table 4. ELECTRICAL CHARACTERISTICS FOR COMMERCIAL AND INDUSTRIAL TEMPERATURE DEVICES

| Parameter | Description | Test Conditions | Min | Max | Unit |
|-----------|----------------------------------|---|-----|----------------|---------------|
| V_{IL} | Input LOW Voltage (Note 3) | | | 0.8 | V |
| V_{IH} | Input HIGH Voltage (Note 3) | | 2.0 | | V |
| I_{IL} | Input LOW Current | $V_{IN} = 0\text{ V}$ | | 50 | μA |
| I_{IH} | Input HIGH Current | $V_{IN} = V_{DD}$ | | 100 | μA |
| V_{OL} | Output LOW Voltage | $I_{OL} = 8\text{ mA} (-1)$ $I_{OL} = 12\text{ mA} (-1H)$ | | 0.4 | V |
| V_{OH} | Output HIGH Voltage | $I_{OH} = -8\text{ mA} (-1)$ $I_{OH} = -12\text{ mA} (-1H)$ | 2.4 | | V |
| I_{DD} | Supply Current (Commercial Temp) | Unloaded outputs at 66.67 MHz, Select inputs at V_{DD} | | 34 | mA |
| I_{DD} | Supply Current (Industrial Temp) | Unloaded outputs at 100 MHz 66.67 MHz 33 MHz Select inputs at V_{DD} or GND, at Room Temp | | 50 34 19 | mA |

3. REF input has a threshold voltage of $V_{DD}/2$.

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Table 5. SWITCHING CHARACTERISTICS (Commercial and Industrial) (Note 4)

| Parameter | Description | Test Conditions | Min | Typ | Max | Unit |
|-------------------|---|---|----------|----------|---------------|------|
| 1/t ₁ | Output Frequency | 30 pF load 10 pF load | 15 15 | | 100 133.33 | MHz |
| 1/t ₁ | Duty Cycle = (t ₂ / t ₁) * 100 (-1, -1H) (-1H) | Measured at 1.4 V, F _{OUT} = 66.67 MHz < 50 MHz | 40 45 | 50 50 | 60 55 | % |
| t ₃ | Output Rise Time (-1) (-1H) | Measured between 0.8 V and 2.0 V | | | 2.5 1.5 | ns |
| t ₄ | Output Fall Time (-1) (-1H) | Measured between 2.0 V and 0.8 V | | | 2.5 1.5 | ns |
| t ₅ | Output-to-Output Skew | All outputs equally loaded | | | 250 | ps |
| t ₆ | Delay, REF Rising Edge to CLKOUT Rising Edge | Measured at V _{DD} /2 | | 0 | ±350 | ps |
| t ₇ | Device-to-Device Skew | Measured at V _{DD} /2 on the CLKOUT pins of the device | | 0 | 700 | ps |
| t _J | Cycle-to-Cycle Jitter | Measured at 66.67 MHz, loaded outputs | | | 200 | ps |
| t _{LOCK} | PLL Lock Time | Stable power supply, valid clock presented on REF pin | | | 1.0 | ms |
| t _{r_in} | REF Input Rise Time | Measured between 0.8 V to 2.0 V | | | 1.0 | ns |
| t _{f_in} | REF Input Rise Fall Time | Measured between 2.0 V to 0.8 V | | | 1.0 | ns |

4. All parameters specified with loaded outputs.

Zero Delay and Skew Control

All outputs should be uniformly loaded to achieve Zero Delay between input and output. Since the CLKOUT pin is the internal feedback to the PLL, its relative loading can adjust the input-output delay.

For applications requiring zero input-output delay, all outputs, including CLKOUT, must be equally loaded. Even if CLKOUT is not used, it must have a capacitive load equal to that on other outputs, for obtaining zero-input-output delay.

SWITCHING WAVEFORMS

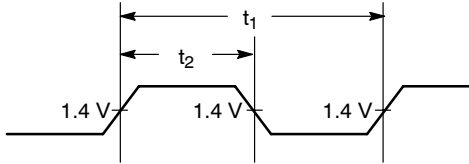


Figure 3. Duty Cycle Timing

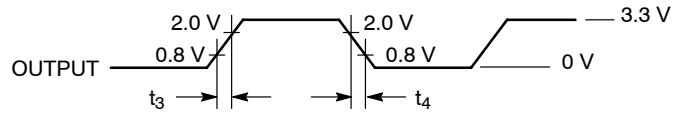


Figure 4. All Outputs Rise/Fall Time

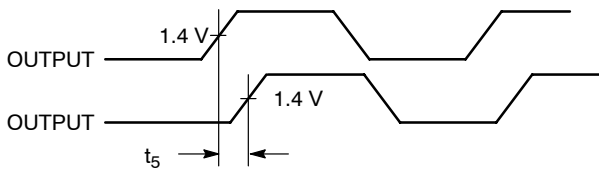


Figure 5. Output - Output Skew

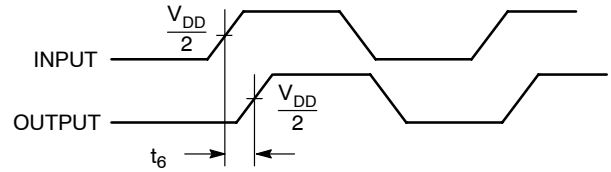


Figure 6. Input - Output Propagation Delay

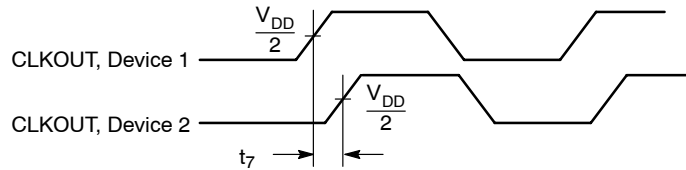


Figure 7. Device - Device Skew

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TEST CIRCUITS

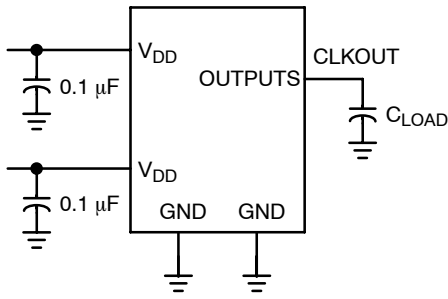


Figure 8. Test Circuit #1

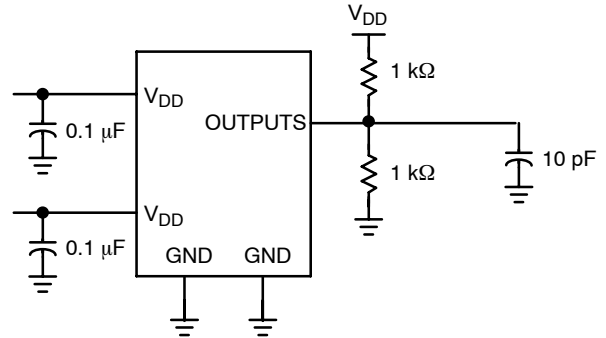


Figure 9. Test Circuit #2
For parameter t_b (output slew rate) on -1H devices

ORDERING INFORMATION

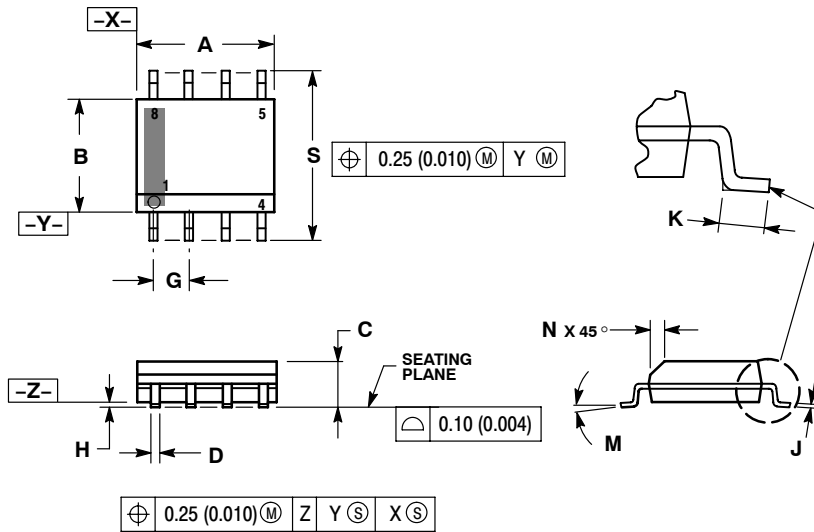
| Device | Marking | Operating Range | Package | Shipping [†] | Availability |
|-----------------|---------|-----------------|-------------------|-----------------------|--------------|
| NB2305AC1DG | 5C1 | Commercial | SOIC-8 (Pb-Free) | 98 Units / Rail | Now |
| NB2305AC1DR2G | 5C1 | Commercial | SOIC-8 (Pb-Free) | 2500 Tape & Reel | Now |
| NB2305AI1DG | 5I1 | Industrial | SOIC-8 (Pb-Free) | 98 Units / Rail | Now |
| NB2305AI1DR2G | 5I1 | Industrial | SOIC-8 (Pb-Free) | 2500 Tape & Reel | Now |
| NB2305AC1HDG | 5C1H | Commercial | SOIC-8 (Pb-Free) | 98 Units / Rail | Now |
| NB2305AC1HDR2G | 5C1H | Commercial | SOIC-8 (Pb-Free) | 2500 Tape & Reel | Now |
| NB2305AI1HDG | 5I1H | Industrial | SOIC-8 (Pb-Free) | 98 Units / Rail | Now |
| NB2305AI1HDR2G | 5I1H | Industrial | SOIC-8 (Pb-Free) | 2500 Tape & Reel | Now |
| NB2305AC1DTG | 5C1 | Commercial | TSSOP-8 (Pb-Free) | 100 Units / Rail | Now |
| NB2305AC1DTR2G | 5C1 | Commercial | TSSOP-8 (Pb-Free) | 2500 Tape & Reel | Now |
| NB2305AI1DTG | 5I1 | Industrial | TSSOP-8 (Pb-Free) | 100 Units / Rail | Now |
| NB2305AI1DTR2G | 5I1 | Industrial | TSSOP-8 (Pb-Free) | 2500 Tape & Reel | Now |
| NB2305AC1HDTG | 5C1H | Commercial | TSSOP-8 (Pb-Free) | 100 Units / Rail | Now |
| NB2305AC1HDTR2G | 5C1H | Commercial | TSSOP-8 (Pb-Free) | 2500 Tape & Reel | Now |
| NB2305AI1HDTG | 5I1H | Industrial | TSSOP-8 (Pb-Free) | 100 Units / Rail | Now |
| NB2305AI1HDTR2G | 5I1H | Industrial | TSSOP-8 (Pb-Free) | 2500 Tape & Reel | Now |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

SOIC-8 NB
CASE 751-07
ISSUE AG

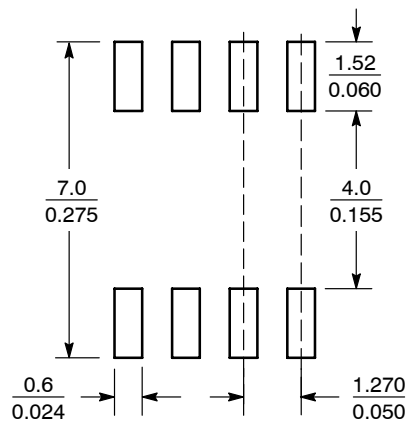


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.80 | 5.00 | 0.189 | 0.197 |
| B | 3.80 | 4.00 | 0.150 | 0.157 |
| C | 1.35 | 1.75 | 0.053 | 0.069 |
| D | 0.33 | 0.51 | 0.013 | 0.020 |
| G | 1.27 BSC | | 0.050 BSC | |
| H | 0.10 | 0.25 | 0.004 | 0.010 |
| J | 0.19 | 0.25 | 0.007 | 0.010 |
| K | 0.40 | 1.27 | 0.016 | 0.050 |
| M | 0° 8° | | 0° 8° | |
| N | 0.25 | 0.50 | 0.010 | 0.020 |
| S | 5.80 | 6.20 | 0.228 | 0.244 |

SOLDERING FOOTPRINT*



SCALE 6:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Данный компонент на территории Российской Федерации

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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